

# SOT1527-2

BGA516, plastic, ball grid array; 516 balls; 1 mm pitch; 27 mm x 27 mm x 1.95 mm body

4 January 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	BGA516
<b>Package style descriptive code</b>	BGA (ball grid array)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MS-034 AAL-1
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	01-02-2016
<b>Manufacturer package code</b>	98ARS10503D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	27	-	mm
package width	-	27	-	mm
package height	-	1.95	-	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	516	-	



2 Package outline

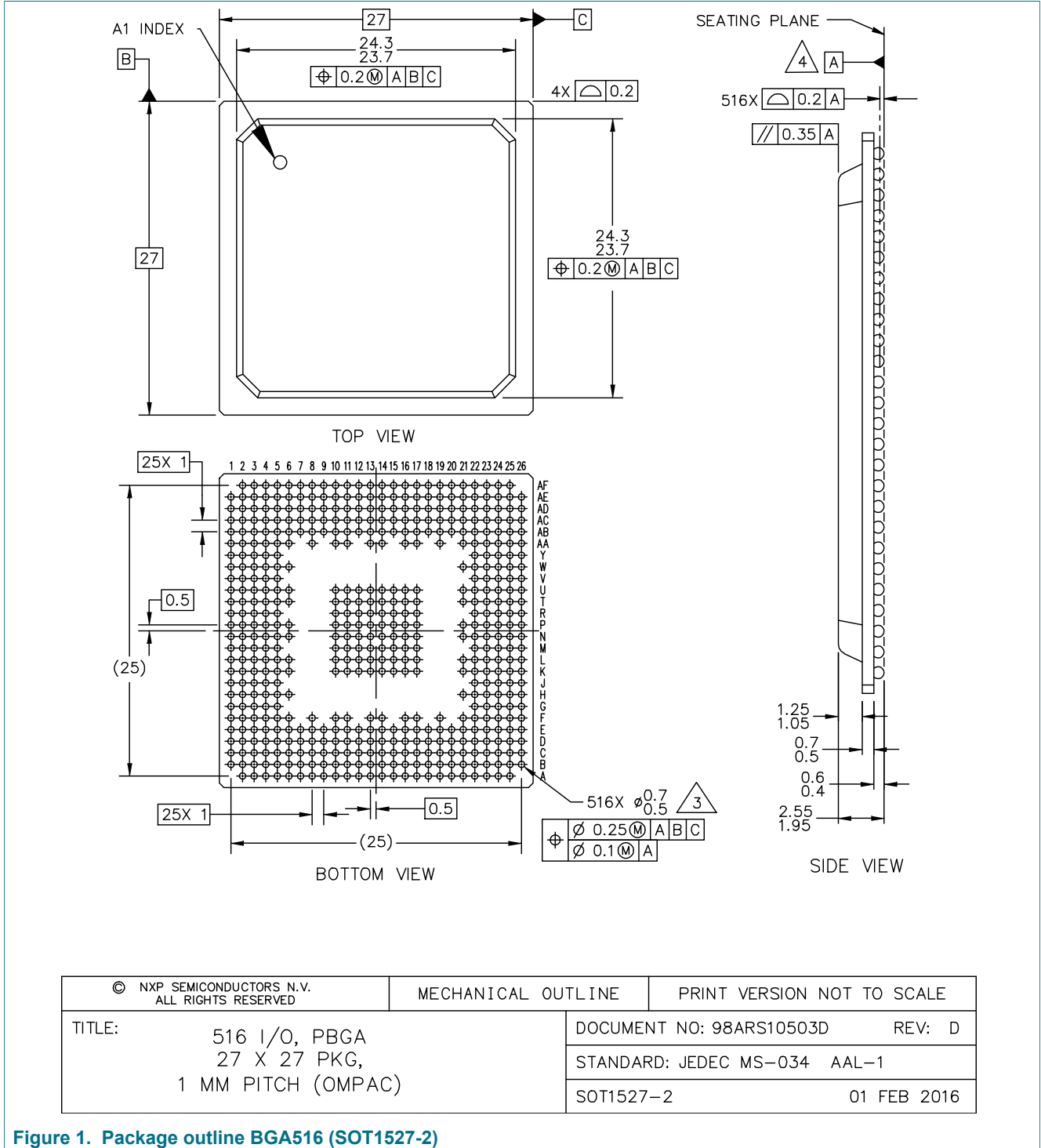


Figure 1. Package outline BGA516 (SOT1527-2)

BGA516, plastic, ball grid array; 516 balls; 1 mm pitch; 27 mm x 27 mm x 1.95 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DELETED

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TITLE: 516 I/O, PBGA 27 X 27 PKG, 1 MM PITCH (OMPAC)	DOCUMENT NO: 98ARS10503D	REV: D
	STANDARD: JEDEC MS-034	AAL-1
	SOT1527-2	01 FEB 2016

Figure 2. Package outline note BGA516 (SOT1527-2)

### 3 Legal information

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